**PCB specifications for MiniScope v1.0 data acquisition board**

**Layer order:**

1 - Top

Inner 2 - DGND Plane (GROUND)

Inner 3 - VDD3V3 Plane (POWER)

4 - Bottom

**Gerber files description:**

Board Outline: DAQ - Board Outline.gbr

Bottom Solder Paste: DAQ - Bottom Copper (Paste).gbr

Bottom Solder Mask DAQ - Bottom Copper (Resist).gbr

Bottom Layer: DAQ - Bottom Copper.gbr

Bottom Silkscreen: DAQ - Bottom Silkscreen.gbr

Inner Layer 2: DAQ - DGND Plane (Powerplane).gbr

Drills: DAQ - Drill Data - [Through Hole].drl

Top Solder Paste: DAQ - Top Copper (Paste).gbr

Top Solder Mask DAQ - Top Copper (Resist).gbr

Top Layer: DAQ - Top Copper.gbr

Top Silkscreen: DAQ - Top Silkscreen.gbr

Inner Layer 3: DAQ - VDD\_3V3 Plane (Powerplane).gbr

**PCB specifications:**

Layers: 4

ITAR: no

Certs: IPC Class 2-A600

AS9100: no

Electrical Test: no

5% OVERAGE: no

Material Type: FR4

Material Thickness: 0.062"

Board Finish: LFSolder

Unit Dimensions: 2.3 in x 2.1 in

Tab Rout: no

Scoring: no

Copper Weight: 1 oz

Inner Copper Weight: 1.0

Solder Mask Sides: Both Sides

Solder Mask Color: Green

Legend Silk Scrn: Both Sides

Legd/Silk Scrn Color: White

Castellated Holes: no

Blind/Buried Vias: None

SM Plugged Via: no

Via-In-Pad: None

Microvias: None

Plated Slots: no

Plated Edges: no

CounterSinks: no

CounterBores: no

CtrSinksPlated: 0

CtrBoresPlated: 0

CtrSinksNon-Pltd: 0

CtrBoresNon-Pltd: 0

Ctrld Dielectric: no

Ctrld Impedance: no

Etchback: no

# Pem Nuts: 0